BONDING HEAD WITH A HEATABLE AND COOLABLE SUCTION MEMBER

ABSTRACT

A bonding head (1) for mounting semiconductor chips on a substrate comprises a bonding head body (2) and a suction member (3) formed of a single piece. The elements necessary for heating, cooling and monitoring the temperature of the suction member (3) are all integrated into the suction member (3), so that neither the heating nor the cooling elements are separated from the semiconductor chip (11) by a surface preventing the heat transfer. The bonding head body (2) contains only the elements necessary for supplying the suction member (3) with electrical power and with the cooling medium.

(Fig. 1)